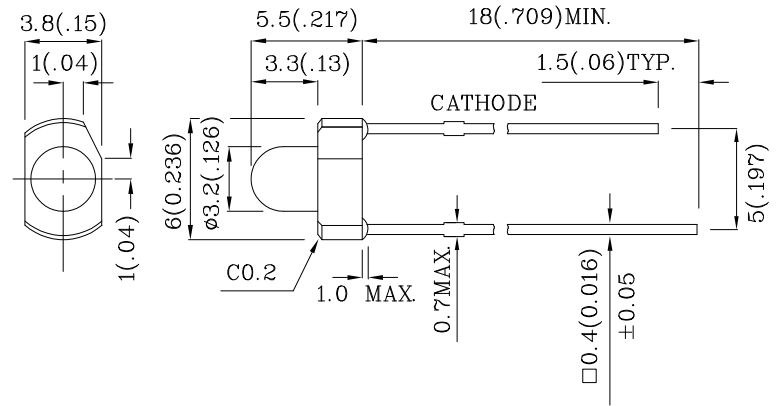


Features

- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- AVAILABLE ON TAPE FOR AUTOMATIC MOUNTING MACHINE.
- LONG LIFE-SOLID STATE RELIABILITY.
- RoHS COMPLIANT.



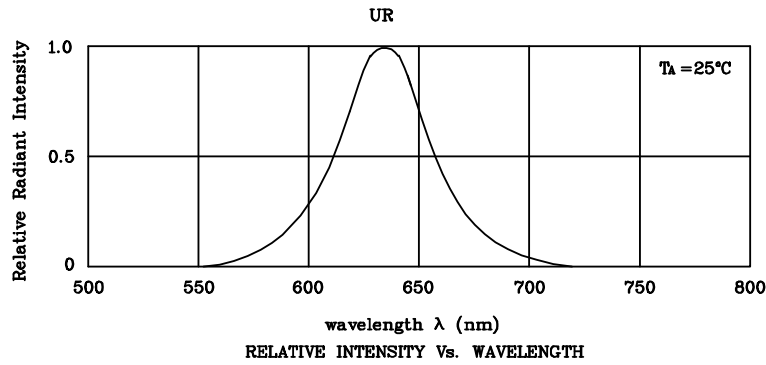
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

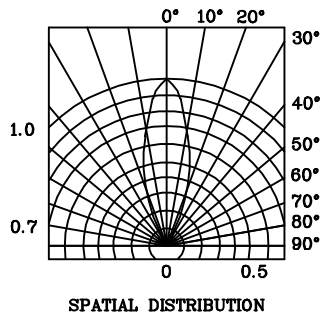
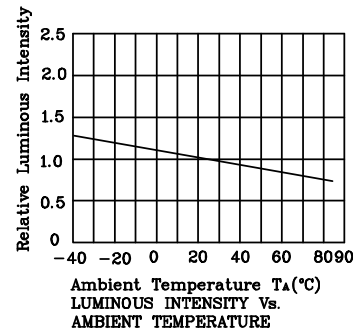
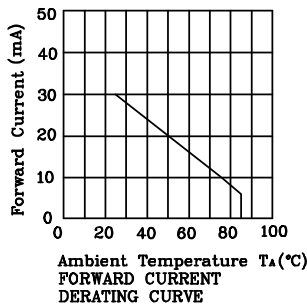
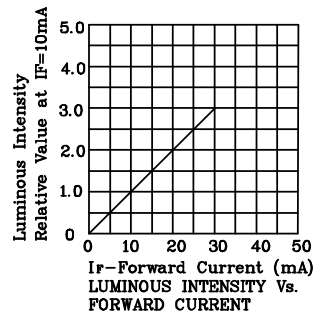
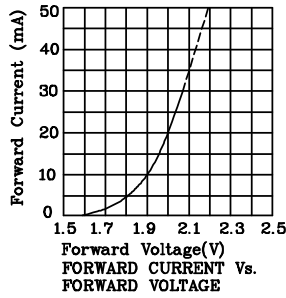
Absolute maximum ratings ($T_A=25^\circ\text{C}$)		UR (GaAsP/GaP)	Unit
Reverse voltage	V_R	5	V
Forward current	I_F	30	mA
Forward current (peak) 1/10Duty cycle 0.1ms pulse width	i_{FS}	160	mA
Power dissipation	P_T	105	mW
Operating temperature	T_A	-40 ~ +85	°C
Storage temperature	T_{stg}	-40 ~ +85	
Lead solder temperature [2mm below package base]	260°C For 3 Seconds		
Lead solder temperature [5mm below package base]	260°C For 5 Seconds		

Operating Characteristics ($T_A=25^\circ\text{C}$)		UR (GaAsP/GaP)	Unit
Forward voltage (typ.) ($I_F=10\text{mA}$)	V_F	1.9	V
Forward voltage (max.) ($I_F=10\text{mA}$)	V_F	2.5	V
Reverse current ($V_R=5\text{V}$)	I_R	10	μA
Wavelength at peak emission ($I_F=10\text{mA}$)	λ_{peak}	627	nm
Wavelength of Dominant emission ($I_F=10\text{mA}$)	λ_D	625	nm
Spectral Line half-width ($I_F=10\text{mA}$)	$\Delta\lambda$	45	nm
Capacitance ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($I_F=10\text{mA}$) mcd		Wavelength nm λ_P	Viewing Angle 2θ 1/2
				min.	typ.		
XLUR25C-1	Red	GaAsP/GaP	Red Transparent	28	89	627	35°



❖ UR



Remarks:

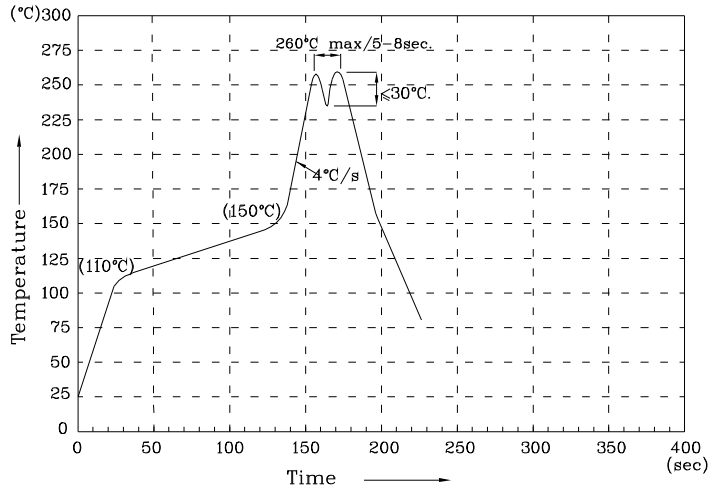
If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

XLUR25C-1

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.